

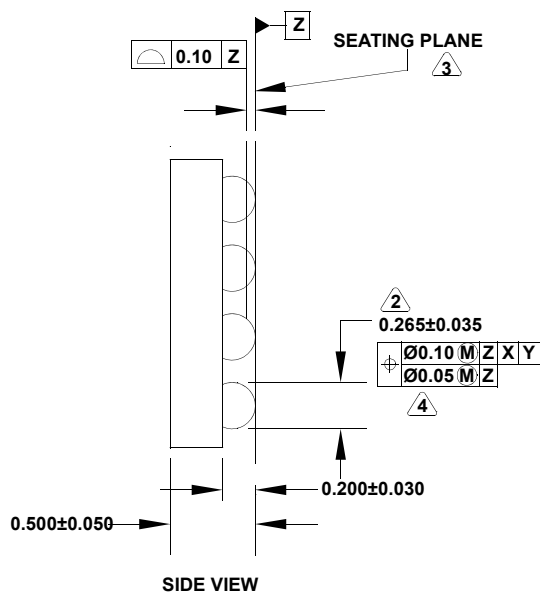
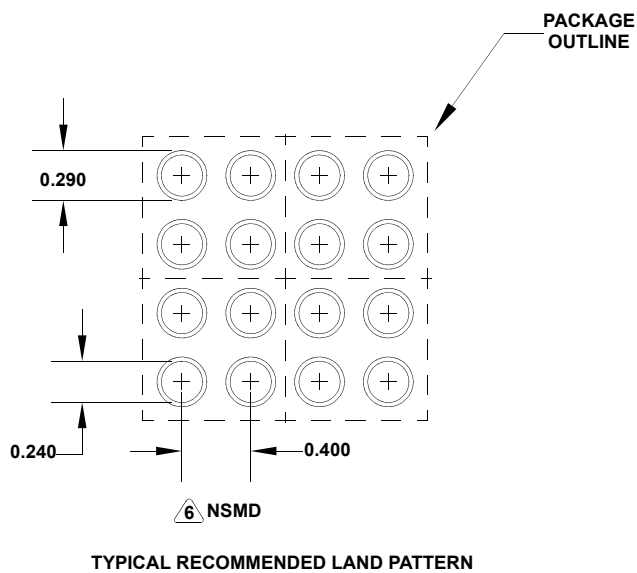
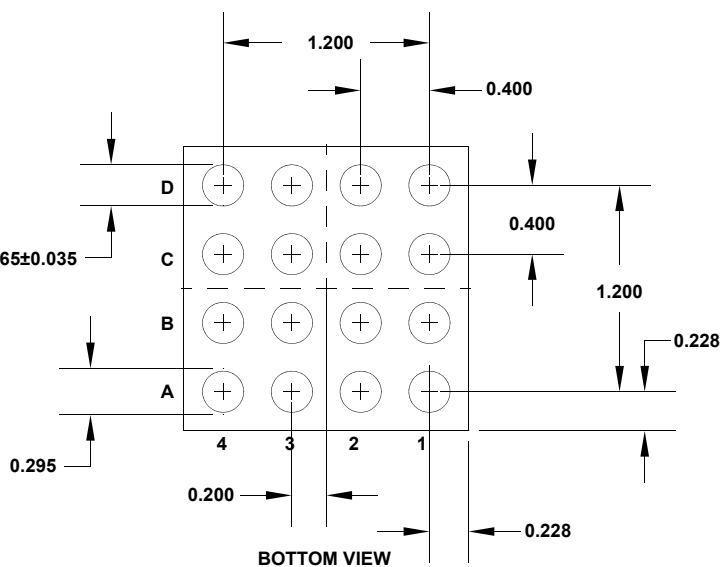
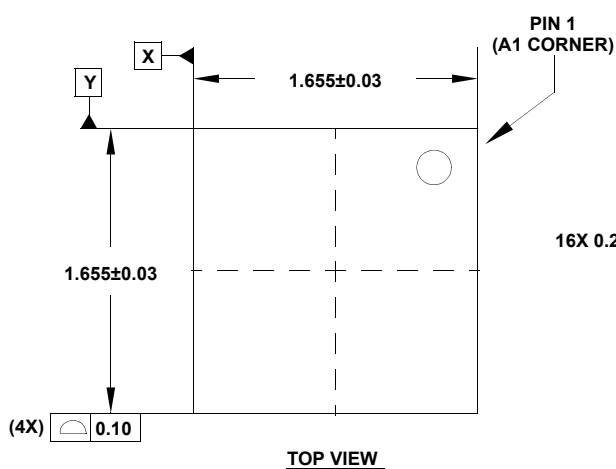
Plastic Packages for Integrated Circuits

Package Outline Drawing

W4x4.16B

4x4 ARRAY 16 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP)

Rev 2, 8/13



NOTES:

1. Dimensions and tolerance and tolerance per ASMEY 14.5 - 1994.
2. Dimension is measured at the maximum bump diameter parallel to primary datum Z .
3. Primary datum Z and seating plane are defined by the spherical crowns of the bump.
4. Bump position designation per JESD 95-1, SPP-010.
5. All dimensions are in millimeters.
6. NSMD refers to non-solder mask defined pad design per Intersil Techbrief www.intersil.com/data/tb/tb451.pdf